

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by

Udo Steinebrunner, Product Manager, -

Declaration effective from: 3 March 2023 [Approved: 3 March 2023, 13:55 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	46.83%	ALUMINIUM	7429-90-5	1.56%
			SILVER, ELEMENTAL	7440-22-4	2.07%
			Elemental silicon	7440-21-3	96.37%
			4,4'-SULFONYLBISANILINE	80-08-0	2.5%
Die attach	Polymeric compounds	0.27%	2,2'-(1,4-Butanediylbis(oxymethylene))bisoxirane	2425-79-8	10%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	20%
			SILVER, ELEMENTAL	7440-22-4	67.5%
			Carbon black	1333-86-4	1%
Encapsulation	EP (Epoxy resin)	28.33%	Silicon Dioxide	7631-86-9	10%
			Epoxy resin 89	26335-32-0	15%
			Quartz sand	60676-86-0	74%
Inner preparation	Copper alloys	1.25%	PALLADIUM, ELEMENTAL	7440-05-3	3%
			COPPER, ELEMENTAL	7440-50-8	97%
			MAGNESIUM, ELEMENTAL	7439-95-4	0.3%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	23.32%	SILVER, ELEMENTAL	7440-22-4	0.8%
			Elemental silicon	7440-21-3	1.2%
			Elemental nickel	7440-02-0	4.2%
			REACH Article 67 Exemption		
			COPPER, ELEMENTAL	7440-50-8	93.5%

Attached parts list

Part number	Part name
0201	Diode SMD